

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
AKIRA HOSOYAMA	04/01/2022
YUJI NAKAURA	04/01/2022
YOSHIKADO YAMAUCHI	04/01/2022
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17705575
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NAME OF SUBMITTER:	JASON H. VICK
SIGNATURE:	/Jason H. Vick/
DATE SIGNED:	04/12/2022
Total Attachments: 2	
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Worldwide Assignment

WHEREAS, I/We Akira HOSOYAMA, Yuji NAKAURA, and Yoshikado YAMAUCHI have made an invention entitled "VIBRATION CONTROL SYSTEM USING KURTOSIS RESPONSE SPECTRUM" for which I/We have filed an application for Letters Patent of the United States on March 28, 2022, under Application No. 17/705,575 and

WHEREAS, Osaka Research Institute of Industrial Science and Technology ("ASSIGNEE"), a corporation or other business entity duly registered in the State/Country of JAPAN, whose postal address is 7-1, Ayumino 2-chome, Izumi-shi, Osaka 5941157, Japan, desires to acquire the entire right, title, and interest in and to the invention, the application, and any Letters Patent to be granted for the invention in the United States and in all foreign countries;

WHEREAS, IMV CORPORATION ("ASSIGNEE"), a corporation or other business entity duly registered in the State/Country of JAPAN, whose postal address is 2-6-10, Takejima, Nishi-yodogawa-ku, Osaka-shi, Osaka 5550011, Japan, desires to acquire the entire right, title, and interest in and to the invention, the application, and any Letters Patent to be granted for the invention in the United States and in all foreign countries; and

NOW, THEREFORE, in consideration of One Dollar (\$1.00) paid to me/us by ASSIGNEE, and other good and valuable consideration, the receipt and sufficiency of which I/We acknowledge, I/We, have sold, assigned, transferred, and conveyed, and do hereby sell, assign, transfer, and convey unto ASSIGNEE, its successors, legal representatives, and assigns: the entire right, title, and interest in and to the invention, the application, all applications claiming benefit of the application, including, but not limited to, all continuation, divisional, and continuation-in-parts of the application, all Letters Patent that may be granted thereon in the United States, Canada and in all foreign countries, and all reissues thereof, together with the right to claim priority under the International Convention in all member countries, and the right of priority; and I/We authorize and request the Director of Patents and Trademarks to issue all Letters Patent for the invention to ASSIGNEE, its successors, legal representatives, and assigns in accordance with the terms of this Assignment;

AND I/We covenant and agree that I/We have the full right to convey the entire right, title, and interest herein assigned and that I/We have not executed and will not execute any assignment or other instrument in conflict with this Assignment;

AND I/We further covenant and agree that upon request by ASSIGNEE, its successors, legal representatives, and/or assigns, and without further consideration, I/We will do all lawful acts that may be necessary or desirable to assist ASSIGNEE, its successors, legal representatives, and/or assigns to obtain and enforce patent protection for the invention in the United States and in all foreign countries, including, but not limited to, communicate with ASSIGNEE, its successors, legal representatives, and/or assigns any facts known to me/us regarding the invention, testify in any legal proceeding, sign all lawful papers, execute

and deliver all papers that may be necessary or desirable to perfect the title to the invention in ASSIGNEE, its successors, legal representatives, and/or assigns, execute all divisional, continuation, and reissue applications, and make all rightful oaths, it being understood that any expense incident to the rendering of such assistance will be borne by ASSIGNEE, its successors, legal representatives, and/or assigns;

AND I/We further hereby authorize ASSIGNEE, or its attorneys or agents, to insert the correct Application Number and filing Date into this Assignment, if none is indicated on that date of my/our execution of this agreement.

I/We have executed this Assignment on the date(s) indicated below.

Signature: Akira Hosoyama
Date: 1. April 2022
Full Name: Akira HOSOYAMA
Address: c/o Osaka Research Institute of Industrial Science and Technology
7-1, Ayumino 2-chome, Izumi-shi,
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JAPAN

Signature: Yuji Nakaura
Date: 1. April 2022
Full Name: YUJI NAKAURA
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2-6-10, Takejima,
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Signature: Yoshikado Yamauchi
Date: 1 April 2022
Full Name: Yoshikado YAMAUCHI
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